

Shenzhen Yajingxin Electron Co.,Ltd CRYSTAL UNIT SPECIFICATIONS

Customer		
Production Name	SMD CRYSTAL 5.0*3.2	
Customer P/N	N/A	
P/N	5032-SMD8.000M20PF	
Revision	A	
Print Date	2017-9-23	

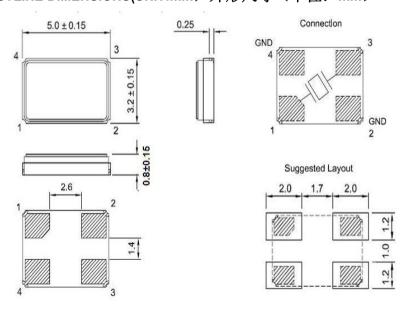
Drawn	Checked	Approved
陳 昭昭	鄭利	李虹

RoHS Compliant

• ELECTRICAL PARAMETERS

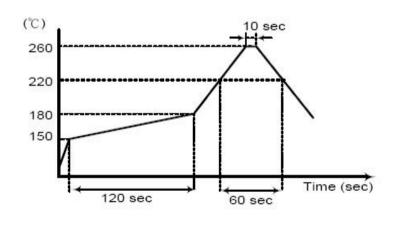
• ELECTRICAL LARABILITERO			
谐振器产品技术指标	Min	Max	Units
1.Holder Type(型号规格)	SI	SEAM 5.0*3.2	
2.Mode of Oscillation(振动模式)	F	`undamenta	al
3. Frequency(标称频率)	8.000	0000	MHz
4.Load Capacitance (CL) (负载电容)	2	20 pF	
5.Drive Level(激励功率)	10	100 uw	
6.Equivalent Resistance(谐振电阻)		100	Ω
7.Shunt Capacitance (Co)(静态电容)	0	7	pF
8.Motional Capacitance (C1) (动态电容)	N,	N/A	
9.Frequency Tolerance at 25℃ (调整频差)	-30	30	ppm
10.Stability over operation temperance (温度频差)) <u>±</u>	± 30 p	
11.Insulation Resistance (at DC 100V)(绝缘电阻)	500		ΜΩ
12.Operating Temperature Range(工作温度范围)		85	$^{\circ}\mathbb{C}$
13. Storage Temperature Range(储存温度范围)	-40	85	$^{\circ}\mathbb{C}$
14. Aging(老化率)	<u>±</u>	± 5 ppm/ye	
15. DLD2		N/A	Ω
16. FLD2 N/A		N/A	ppm
17. RLD2		N/A	Ω
18. SPDB N/A		N/A	db
19.0ther(其它)		N/A	

OUTLINE DIMENSIONS(UNIT:mm) 外形尺寸(单位: mm)

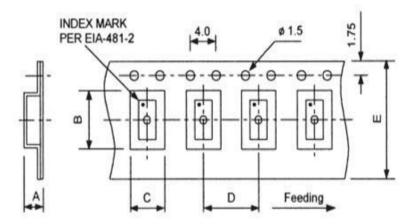


● SUGGESTED REFLOW PROFILE (回流焊曲线图) Total time:200sec.Max. (总时间: 200秒 最大) Solder melting point:220℃(熔点220 ℃)

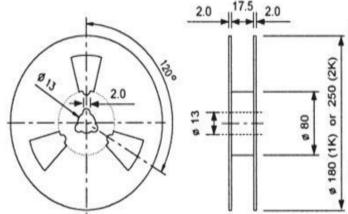
Profiles Feature(特性)		Pb-Free Assembly
Average Ramp-up Rate(Ts max to Tp)平均升温速度		3℃/second Max
Preheat	预热	
■ Temperature Min (Ts min)	最低温度	125℃
■ Temperature Max (Ts max)	最高温度	200℃
■ Time (ts min to ts max)	从最低到最高时间	(60~180) seconds
Time maintained above	维持上述时间	
■ Temperature(T1)	温度	217℃
■ Time(tp)	时间	(60~150) seconds
Peak/Classification Temperature(Tp)	最高点温度	260 ℃
Time within 5°C of actual Peak Temperature(tp)	高温维持时间	(20~40) seconds
Ramp-down rate	降温速度	6℃/second max
Time 25℃ to Peak Temperature	从25℃到最高温度的时间	8 minutes max
Suggest reflow times	建议 reflow次数	3 Times max



● PACKING(包装) 1Kpcs/REEL



SIZE
A 1.7
B 5.45
C 3.65
D 8.0
E 12.0
IK



REMARK:

- 230 mm (9.05) minimum leader which consist of carrier and/or cover tape followed by a minimum of 160 mm (6.3) of empty carrier tape sealed with cover tape.
- 160 mm (6.3) minimum trailer of empty carrier tape sealed with cover tape.

● RELIABILITY SPECIFICATIONS(信赖度试验)

No	Test Item(测试项目)	Test Conditions(测试条件)	Reference(参考)
1	High Temperature High Humidity Storage (高温、高湿、储存)	Temperature: 85℃±3℃ 温度: 85℃±3℃ Relative Humidity:85%RH 相对湿度: 85%RH Time: 96 Hours 时间: 96小时	JIS C5023
2	High Temperature Storage (高温储存)	Temperature: 125℃±3℃ 温度:125℃±3℃ Time: 96 Hours 时间:96 小时	MIL-STD-883E Method 1005.8
3	Low Temperature Storage (低温储存)	Temperature: -40℃±3℃ 温度: -40℃±3℃ Time: 96Hours 时间: 96小时	MIL-STD-883E Method 1013
4	Thermal Shock (温度冲击)	Temperature1:-55℃±5℃ 温度1:-55℃±5℃ Temperature2:85℃±5℃ 温度2: 85℃±5℃ Temperature change between T1 and T2 5 min T1和T2温度在5分钟内改变 10cycles maintain T1 and T2 for 30 minutes each mone 每次循环30分钟共10次	MIL-STD-202F Method 107 Condition A
5	RESISTANCE TO SOLDER HEAT (耐焊接热)	Solder Temperature: 260℃±5℃ 焊槽温度:260℃±5℃ Time: 10±1 Seconds 时间: 10±1秒	MIL-STD-202F Method 210E
6	Solderability(可焊性)	The solder pot temperature is 245±5℃, dwell time 5±0.5se245±5℃焊锡槽浸润5±0.5秒	J-STD-002B
7	Drop Test (落下试验)	3 Times Free Fall from 75cm height table to 3cm thickness hard wood board 从75cm高度3次跌落到3cm厚硬质木板上	JIS C6701
8	MECHANICAL SHOCK (机械冲击)	Half sine wave,1000 G 半正弦波,加速度1000G 3 Times for all 3 directions X、Y、Z 三个相互垂直方向各三次	MIL-STD-202F Method 213B
9	Vibration (机械振动)	Frequency Range: 10Hz~55Hz 频率范围: 10Hz~55Hz Amplitude: 0.75mm 振幅: 0.75mm 2 Hours in each direction, total 6 Hours X、Y、Z 三个相互垂直方向各振动2小时	MIL-STD-883E Method 2007.3
10	Leakage Test (气密性)	Take measurements with a helium Leakage detector 氦质检漏 Leakage Rate≤1×10 ⁻³ Pa cm ³ /s 漏率≤1×10 ⁻³ Pa cm ³ /s	MIL-STD-883E